

FEATURES

- 2.1 Ω on resistance
- 0.5 Ω maximum on-resistance flatness at 25°C
- Up to 390 mA continuous current
- Fully specified at +12 V, ± 15 V, ± 5 V
- No V_L supply required
- 3 V logic-compatible inputs
- Rail-to-rail operation
- 8-lead MSOP and 8-lead, 3 mm \times 2 mm LFCSP

APPLICATIONS

- Automatic test equipment
- Data acquisition systems
- Battery-powered systems
- Relay replacements
- Sample-and-hold systems
- Audio signal routing
- Video signal routing
- Communication systems

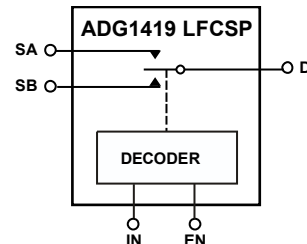
GENERAL DESCRIPTION

The [ADG1419](#) is a monolithic *i*CMOS® device containing a single-pole/double-throw (SPDT) switch. An EN input on the LFCSP is used to enable or disable the device. When disabled, all channels are switched off.

The industrial CMOS (*i*CMOS) modular manufacturing process combines high voltage, complementary metal-oxide semiconductor (CMOS) and bipolar technologies. It enables the development of a wide range of high performance analog ICs capable of 33 V operation in a footprint that no other generation of high voltage parts has achieved. Unlike analog ICs using conventional CMOS processes, *i*CMOS components can tolerate high supply voltages while providing increased performance, dramatically lower power consumption, and reduced package size.

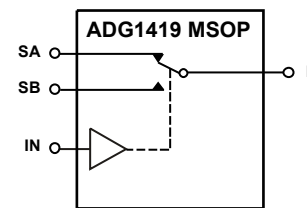
The on-resistance profile is very flat over the full analog input range, ensuring excellent linearity and low distortion when switching audio signals. The *i*CMOS construction ensures ultralow power dissipation, making the part ideally suited for portable and battery-powered instruments.

FUNCTIONAL BLOCK DIAGRAMS



SWITCHES SHOWN FOR A LOGIC 0 INPUT.

Figure 1. 8-Lead LFCSP (CP-8-4)



SWITCHES SHOWN FOR A LOGIC 0 INPUT.

Figure 2. 8-Lead MSOP (RM-8)

Each switch conducts equally well in both directions when on and has an input signal range that extends to the supplies. In the off condition, signal levels up to the supplies are blocked. The [ADG1419](#) exhibits break-before-make switching action for use in multiplexer applications.

PRODUCT HIGHLIGHTS

1. 2.4 Ω maximum on resistance at 25°C.
2. Minimum distortion.
3. 3 V logic-compatible digital inputs: $V_{INH} = 2.0$ V, $V_{INL} = 0.8$ V.
4. No V_L logic power supply required.
5. 8-lead MSOP and 8-lead, 3 mm \times 2 mm LFCSP.

ADG1419* PRODUCT PAGE QUICK LINKS

Last Content Update: 02/23/2017

COMPARABLE PARTS

View a parametric search of comparable parts.

EVALUATION KITS

- Evaluation Board for 8 lead MSOP Devices in the Switch/Mux Portfolio

DOCUMENTATION

Data Sheet

- ADG1419: 2.1 Ω On Resistance, ± 15 V/+12 V/ ± 5 V iCMOS SPDT Switch Data Sheet

User Guides

- UG-893: Evaluating the 8-Lead MSOP Devices in the Switch/Mux Portfolio

TOOLS AND SIMULATIONS

- ADG1419 IBIS Model

REFERENCE DESIGNS

- CN0359

REFERENCE MATERIALS

Informational

- iCMOS Technology Enabling the +/-10V World

Product Selection Guide

- Switches and Multiplexers Product Selection Guide

DESIGN RESOURCES

- ADG1419 Material Declaration
- PCN-PDN Information
- Quality And Reliability
- Symbols and Footprints

DISCUSSIONS

View all ADG1419 EngineerZone Discussions.

SAMPLE AND BUY

Visit the product page to see pricing options.

TECHNICAL SUPPORT

Submit a technical question or find your regional support number.

DOCUMENT FEEDBACK

Submit feedback for this data sheet.

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REVISION HISTORY

6/2016—Rev. 0 to Rev. A

| | |
|--|---|
| Changes to Table 7..... | 8 |
| Deleted Table 9; Renumbered Sequentially | 8 |
| Change to Figure 6 | 9 |

10/2009—Revision 0: Initial Version

SPECIFICATIONS

±15 V DUAL SUPPLY

$V_{DD} = +15\text{ V} \pm 10\%$, $V_{SS} = -15\text{ V} \pm 10\%$, $GND = 0\text{ V}$, unless otherwise noted.

Table 1.

| Parameter | 25°C | -40°C to +85°C | -40°C to +125°C | Unit | Test Conditions/Comments |
|---|-----------|----------------|----------------------|-------------------|--|
| ANALOG SWITCH | | | | | |
| Analog Signal Range | | | V_{DD} to V_{SS} | V | |
| On Resistance, R_{ON} | 2.1 | | | Ω typ | $V_S = \pm 10\text{ V}$, $I_S = -10\text{ mA}$; see Figure 22 |
| | 2.4 | 2.8 | 3.2 | Ω max | $V_{DD} = +13.5\text{ V}$, $V_{SS} = -13.5\text{ V}$ |
| On-Resistance Match Between Channels, ΔR_{ON} | 0.05 | | | Ω typ | $V_S = \pm 10\text{ V}$, $I_S = -10\text{ mA}$ |
| | 0.2 | 0.25 | 0.3 | Ω max | |
| On-Resistance Flatness, $R_{FLAT(ON)}$ | 0.4 | | | Ω typ | $V_S = \pm 10\text{ V}$, $I_S = -10\text{ mA}$ |
| | 0.5 | 0.6 | 0.65 | Ω max | |
| LEAKAGE CURRENTS | | | | | |
| Source Off Leakage, I_S (Off) | ± 0.1 | | | nA typ | $V_{DD} = +16.5\text{ V}$, $V_{SS} = -16.5\text{ V}$ |
| | ± 0.5 | ± 2 | ± 75 | nA max | $V_S = \pm 10\text{ V}$, $V_D = \pm 10\text{ V}$; see Figure 23 |
| Drain Off Leakage, I_D (Off) | ± 0.2 | | | nA typ | $V_S = \pm 10\text{ V}$, $V_D = \pm 10\text{ V}$; see Figure 23 |
| | ± 0.6 | ± 3 | ± 100 | nA max | |
| Channel On Leakage, I_D , I_S (On) | ± 0.2 | | | nA typ | $V_S = V_D = \pm 10\text{ V}$; see Figure 24 |
| | ± 1 | ± 3 | ± 100 | nA max | |
| DIGITAL INPUTS | | | | | |
| Input High Voltage, V_{INH} | | | 2.0 | V min | |
| Input Low Voltage, V_{INL} | | | 0.8 | V max | |
| Input Current, I_{INL} or I_{INH} | 0.005 | | | μA typ | $V_{IN} = V_{GND}$ or V_{DD} |
| | | | ± 0.1 | μA max | |
| Digital Input Capacitance, C_{IN} | 4 | | | pF typ | |
| DYNAMIC CHARACTERISTICS¹ | | | | | |
| Transition Time, $t_{TRANSITION}$ | 130 | | | ns typ | $R_L = 300\ \Omega$, $C_L = 35\text{ pF}$ |
| | 155 | 190 | 220 | ns max | $V_S = +10\text{ V}$; see Figure 25 |
| t_{ON} (EN) | 85 | | | ns typ | $R_L = 300\ \Omega$, $C_L = 35\text{ pF}$ |
| | 110 | 125 | 140 | ns max | $V_S = 10\text{ V}$; see Figure 27 |
| t_{OFF} (EN) | 115 | | | ns typ | $R_L = 300\ \Omega$, $C_L = 35\text{ pF}$ |
| | 140 | 160 | 180 | ns max | $V_S = 10\text{ V}$; see Figure 27 |
| Break-Before-Make Time Delay, t_D | 15 | | | ns typ | $R_L = 300\ \Omega$, $C_L = 35\text{ pF}$ |
| | | | 8 | ns min | $V_{S1} = V_{S2} = 10\text{ V}$; see Figure 26 |
| Charge Injection | -16 | | | pC typ | $V_S = 0\text{ V}$, $R_S = 0\ \Omega$, $C_L = 1\text{ nF}$; see Figure 28 |
| Off Isolation | -64 | | | dB typ | $R_L = 50\ \Omega$, $C_L = 5\text{ pF}$, $f = 1\text{ MHz}$; see Figure 29 |
| Channel-to-Channel Crosstalk | -64 | | | dB typ | $R_L = 50\ \Omega$, $C_L = 5\text{ pF}$, $f = 1\text{ MHz}$; see Figure 30 |
| Total Harmonic Distortion Plus Noise (THD + N) | 0.016 | | | % typ | $R_L = 10\text{ k}\Omega$, 5 V rms , $f = 20\text{ Hz}$ to 20 kHz ; see Figure 32 |
| -3 dB Bandwidth | 135 | | | MHz typ | $R_L = 50\ \Omega$, $C_L = 5\text{ pF}$; see Figure 31 |
| Insertion Loss | 0.16 | | | dB typ | $R_L = 50\ \Omega$, $C_L = 5\text{ pF}$, $f = 1\text{ MHz}$; see Figure 31 |
| C_S (Off) | 19 | | | pF typ | $f = 1\text{ MHz}$; $V_S = 0\text{ V}$ |
| C_D (Off) | 44 | | | pF typ | $f = 1\text{ MHz}$; $V_S = 0\text{ V}$ |
| C_D , C_S (On) | 114 | | | pF typ | $f = 1\text{ MHz}$; $V_S = 0\text{ V}$ |

| Parameter | 25°C | -40°C to +85°C | -40°C to +125°C | Unit | Test Conditions/Comments |
|---------------------------|-------|----------------|--------------------|--|---|
| POWER REQUIREMENTS | | | | | |
| I_{DD} | 0.002 | | 1.0 | μA typ μA max | $V_{DD} = +16.5\text{ V}$, $V_{SS} = -16.5\text{ V}$ Digital inputs = 0 V or V_{DD} |
| I_{DD} , 8-Lead MSOP | 58 | | 95 | μA typ μA max | Digital inputs = 5 V |
| I_{DD} , 8-Lead LFCSP | 120 | | 190 | μA typ μA max | Digital inputs = 5 V |
| I_{SS} | 0.002 | | 1.0 | μA typ μA max | Digital inputs = 0 V, 5 V, or V_{DD} |
| V_{DD}/V_{SS} | | | $\pm 4.5/\pm 16.5$ | V min/max | Ground = 0 V |

¹ Guaranteed by design, not subject to production test.

+12 V SINGLE SUPPLY

$V_{DD} = 12\text{ V} \pm 10\%$, $V_{SS} = 0\text{ V}$, GND = 0 V, unless otherwise noted.

Table 2.

| Parameter | 25°C | -40°C to +85°C | -40°C to +125°C | Unit | Test Conditions/Comments |
|---|------------------------|----------------|-----------------|--|--|
| ANALOG SWITCH | | | | | |
| Analog Signal Range | | | 0 V to V_{DD} | V | |
| On Resistance, R_{ON} | 4 | | | Ω typ | $V_S = 0\text{ V}$ to 10 V, $I_S = -10\text{ mA}$; see Figure 22 |
| On-Resistance Match Between Channels, ΔR_{ON} | 4.6 0.08 | 5.5 | 6.2 | Ω max Ω typ | $V_{DD} = +10.8\text{ V}$, $V_{SS} = 0\text{ V}$ $V_S = 0\text{ V}$ to 10 V, $I_S = -10\text{ mA}$ |
| On-Resistance Flatness, $R_{FLAT(ON)}$ | 0.25 1.2 1.5 | 0.3 1.75 | 0.35 1.9 | Ω max Ω typ Ω max | $V_S = 0\text{ V}$ to 10 V, $I_S = -10\text{ mA}$ |
| LEAKAGE CURRENTS | | | | | |
| Source Off Leakage, I_S (Off) | ± 0.1 ± 0.5 | ± 2 | ± 75 | nA typ nA max | $V_{DD} = +13.2\text{ V}$, $V_{SS} = 0\text{ V}$ $V_S = 1\text{ V}/10\text{ V}$, $V_D = 10\text{ V}/1\text{ V}$; see Figure 23 |
| Drain Off Leakage, I_D (Off) | ± 0.2 ± 0.6 | ± 3 | ± 100 | nA typ nA max | $V_S = 1\text{ V}/10\text{ V}$, $V_D = 10\text{ V}/1\text{ V}$; see Figure 23 |
| Channel On Leakage, I_D , I_S (On) | ± 0.2 ± 1 | ± 3 | ± 100 | nA typ nA max | $V_S = V_D = 1\text{ V}$ or 10 V; see Figure 24 |
| DIGITAL INPUTS | | | | | |
| Input High Voltage, V_{INH} | | | 2.0 | V min | |
| Input Low Voltage, V_{INL} | | | 0.8 | V max | |
| Input Current, I_{INL} or I_{INH} | 0.005 | | ± 0.1 | μA typ μA max | $V_{IN} = V_{GND}$ or V_{DD} |
| Digital Input Capacitance, C_{IN} | 4 | | | pF typ | |
| DYNAMIC CHARACTERISTICS¹ | | | | | |
| Transition Time, $t_{TRANSITION}$ | 200 255 | 265 | 370 | ns typ ns max | $R_L = 300\ \Omega$, $C_L = 35\text{ pF}$ $V_S = 8\text{ V}$; see Figure 25 |
| t_{ON} (EN) | 145 190 | 220 | 245 | ns typ ns max | $R_L = 300\ \Omega$, $C_L = 35\text{ pF}$ $V_S = 8\text{ V}$; see Figure 27 |
| t_{OFF} (EN) | 130 170 | 205 | 220 | ns typ ns max | $R_L = 300\ \Omega$, $C_L = 35\text{ pF}$ $V_S = 8\text{ V}$; see Figure 27 |
| Break-Before-Make Time Delay, t_D | 55 | | 33 | ns typ ns min | $R_L = 300\ \Omega$, $C_L = 35\text{ pF}$ $V_{S1} = V_{S2} = 8\text{ V}$; see Figure 26 |
| Charge Injection | 13 | | | pC typ | $V_S = 6\text{ V}$, $R_S = 0\ \Omega$, $C_L = 1\text{ nF}$; see Figure 28 |
| Off Isolation | -60 | | | dB typ | $R_L = 50\ \Omega$, $C_L = 5\text{ pF}$, $f = 1\text{ MHz}$; see Figure 29 |

| Parameter | 25°C | -40°C to +85°C | -40°C to +125°C | Unit | Test Conditions/Comments |
|------------------------------|-------|----------------|-----------------|-------------------|--|
| Channel-to-Channel Crosstalk | -60 | | | dB typ | $R_L = 50 \Omega$, $C_L = 5 \text{ pF}$, $f = 1 \text{ MHz}$; see Figure 30 |
| -3 dB Bandwidth | 95 | | | MHz typ | $R_L = 50 \Omega$, $C_L = 5 \text{ pF}$; see Figure 31 |
| Insertion Loss | 0.3 | | | dB typ | $R_L = 50 \Omega$, $C_L = 5 \text{ pF}$, $f = 1 \text{ MHz}$; see Figure 31 |
| C_S (Off) | 32 | | | pF typ | $f = 1 \text{ MHz}$; $V_S = 6 \text{ V}$ |
| C_D (Off) | 72 | | | pF typ | $f = 1 \text{ MHz}$; $V_S = 6 \text{ V}$ |
| C_D , C_S (On) | 123 | | | pF typ | $f = 1 \text{ MHz}$; $V_S = 6 \text{ V}$ |
| POWER REQUIREMENTS | | | | | |
| I_{DD} | 0.001 | | | μA typ | $V_{DD} = 13.2 \text{ V}$ Digital inputs = 0 V or V_{DD} |
| I_{DD} , 8-Lead MSOP | 58 | | 1.0 | μA max | Digital inputs = 5 V |
| I_{DD} , 8-Lead LFCSOP | 120 | | 95 | μA max | Digital inputs = 5 V |
| V_{DD} | | | 190 | μA max | Ground = 0 V, $V_{SS} = 0 \text{ V}$ |
| | | | 5/16.5 | V min/max | |

¹ Guaranteed by design, not subject to production test.

±5 V DUAL SUPPLY

$V_{DD} = +5 \text{ V} \pm 10\%$, $V_{SS} = -5 \text{ V} \pm 10\%$, GND = 0 V, unless otherwise noted.

Table 3.

| Parameter | 25°C | -40°C to +85°C | -40°C to +125°C | Unit | Test Conditions/Comments |
|---|-----------|----------------|----------------------|-------------------|--|
| ANALOG SWITCH | | | | | |
| Analog Signal Range | | | V_{DD} to V_{SS} | V | |
| On Resistance, R_{ON} | 4.5 | | | Ω typ | $V_S = \pm 4.5 \text{ V}$, $I_S = -10 \text{ mA}$; see Figure 22 |
| | 5.2 | 6.2 | 7 | Ω max | $V_{DD} = +4.5 \text{ V}$, $V_{SS} = -4.5 \text{ V}$ |
| On-Resistance Match Between Channels, ΔR_{ON} | 0.1 | | | Ω typ | $V_S = \pm 4.5 \text{ V}$, $I_S = -10 \text{ mA}$ |
| | 0.3 | 0.35 | 0.4 | Ω max | |
| On-Resistance Flatness, $R_{FLAT(ON)}$ | 1.3 | | | Ω typ | $V_S = \pm 4.5 \text{ V}$, $I_S = -10 \text{ mA}$ |
| | 1.6 | 1.85 | 2 | Ω max | |
| LEAKAGE CURRENTS | | | | | |
| Source Off Leakage, I_S (Off) | ± 0.1 | | | nA typ | $V_{DD} = +5.5 \text{ V}$, $V_{SS} = -5.5 \text{ V}$ $V_S = \pm 4.5 \text{ V}$, $V_D = \mp 4.5 \text{ V}$; see Figure 23 |
| | ± 0.5 | ± 2 | ± 75 | nA max | |
| Drain Off Leakage, I_D (Off) | ± 0.1 | | | nA typ | $V_S = \pm 4.5 \text{ V}$, $V_D = \mp 4.5 \text{ V}$; see Figure 23 |
| | ± 0.6 | ± 3 | ± 100 | nA max | |
| Channel On Leakage, I_D , I_S (On) | ± 0.1 | | | nA typ | $V_S = V_D = \pm 4.5 \text{ V}$; see Figure 24 |
| | ± 1 | ± 3 | ± 100 | nA max | |
| DIGITAL INPUTS | | | | | |
| Input High Voltage, V_{INH} | | | 2.0 | V min | |
| Input Low Voltage, V_{INL} | | | 0.8 | V max | |
| Input Current, I_{INL} or I_{INH} | 0.001 | | | μA typ | $V_{IN} = V_{GND}$ or V_{DD} |
| | | | ± 0.1 | μA max | |
| Digital Input Capacitance, C_{IN} | 4 | | | pF typ | |

| Parameter | 25°C | -40°C to +85°C | -40°C to +125°C | Unit | Test Conditions/Comments |
|--|-------|----------------|--------------------|--|--|
| DYNAMIC CHARACTERISTICS¹ | | | | | |
| Transition Time, $t_{\text{TRANSITION}}$ | 310 | | | ns typ | $R_L = 300 \Omega$, $C_L = 35 \text{ pF}$ |
| | 410 | 495 | 560 | ns max | $V_S = 3 \text{ V}$; see Figure 25 |
| $t_{\text{ON}} (\text{EN})$ | 230 | | | ns typ | $R_L = 300 \Omega$, $C_L = 35 \text{ pF}$ |
| | 305 | 355 | 390 | ns max | $V_S = 3 \text{ V}$; see Figure 27 |
| $t_{\text{OFF}} (\text{EN})$ | 220 | | | ns typ | $R_L = 300 \Omega$, $C_L = 35 \text{ pF}$ |
| | 290 | 335 | 365 | ns max | $V_S = 3 \text{ V}$; see Figure 27 |
| Break-Before-Make Time Delay, t_D | 65 | | | ns typ | $R_L = 300 \Omega$, $C_L = 35 \text{ pF}$ |
| | | | 31 | ns min | $V_{S1} = V_{S2} = 3 \text{ V}$; see Figure 26 |
| Charge Injection | 59 | | | pC typ | $V_S = 0 \text{ V}$, $R_S = 0 \Omega$, $C_L = 1 \text{ nF}$; see Figure 28 |
| Off Isolation | -60 | | | dB typ | $R_L = 50 \Omega$, $C_L = 5 \text{ pF}$, $f = 1 \text{ MHz}$; see Figure 29 |
| Channel-to-Channel Crosstalk | -60 | | | dB typ | $R_L = 50 \Omega$, $C_L = 5 \text{ pF}$, $f = 1 \text{ MHz}$; see Figure 30 |
| Total Harmonic Distortion Plus Noise | 0.04 | | | % typ | $R_L = 10 \text{ k}\Omega$, 5 V p-p , $f = 20 \text{ Hz to } 20 \text{ kHz}$; see Figure 32 |
| -3 dB Bandwidth | 105 | | | MHz typ | $R_L = 50 \Omega$, $C_L = 5 \text{ pF}$; see Figure 31 |
| Insertion Loss | 0.28 | | | dB typ | $R_L = 50 \Omega$, $C_L = 5 \text{ pF}$, $f = 1 \text{ MHz}$; see Figure 31 |
| C_S (Off) | 26 | | | pF typ | $V_S = 0 \text{ V}$, $f = 1 \text{ MHz}$ |
| C_D (Off) | 62 | | | pF typ | $V_S = 0 \text{ V}$, $f = 1 \text{ MHz}$ |
| C_D , C_S (On) | 128 | | | pF typ | $V_S = 0 \text{ V}$, $f = 1 \text{ MHz}$ |
| POWER REQUIREMENTS | | | | | |
| I_{DD} | 0.001 | | 1.0 | $\mu\text{A typ}$ $\mu\text{A max}$ | $V_{\text{DD}} = +5.5 \text{ V}$, $V_{\text{SS}} = -5.5 \text{ V}$ Digital inputs = 0 V or V_{DD} |
| I_{SS} | 0.001 | | 1.0 | $\mu\text{A typ}$ $\mu\text{A max}$ | Digital inputs = 0 V or V_{DD} |
| $V_{\text{DD}}/V_{\text{SS}}$ | | | $\pm 4.5/\pm 16.5$ | V min/max | Ground = 0 V |

¹ Guaranteed by design, not subject to production test.

CONTINUOUS CURRENT PER CHANNEL, S OR D

Table 4.

| Parameter | 25°C | 85°C | 125°C | Unit | Test Conditions/Comments |
|--|------|------|-------|------------|---|
| CONTINUOUS CURRENT PER CHANNEL¹ | | | | | |
| $\pm 15 \text{ V Dual Supply}$ | | | | | $V_{\text{DD}} = +13.5 \text{ V}$, $V_{\text{SS}} = -13.5 \text{ V}$ |
| 8-Lead MSOP ($\theta_{\text{JA}} = 206^\circ\text{C/W}$) | 215 | 135 | 80 | mA maximum | |
| 8-Lead LFCSP ($\theta_{\text{JA}} = 50.8^\circ\text{C/W}$) | 390 | 215 | 100 | mA maximum | |
| $+12 \text{ V Single Supply}$ | | | | | $V_{\text{DD}} = 10.8 \text{ V}$, $V_{\text{SS}} = 0 \text{ V}$ |
| 8-Lead MSOP ($\theta_{\text{JA}} = 206^\circ\text{C/W}$) | 175 | 115 | 70 | mA maximum | |
| 8-Lead LFCSP ($\theta_{\text{JA}} = 50.8^\circ\text{C/W}$) | 320 | 185 | 95 | mA maximum | |
| $\pm 5 \text{ V Dual Supply}$ | | | | | $V_{\text{DD}} = +4.5 \text{ V}$, $V_{\text{SS}} = -4.5 \text{ V}$ |
| 8-Lead MSOP ($\theta_{\text{JA}} = 206^\circ\text{C/W}$) | 165 | 110 | 70 | mA maximum | |
| 8-Lead LFCSP ($\theta_{\text{JA}} = 50.8^\circ\text{C/W}$) | 310 | 180 | 95 | mA maximum | |

¹ Guaranteed by design, not subject to production test.

ABSOLUTE MAXIMUM RATINGS

$T_A = 25^\circ\text{C}$, unless otherwise noted.

Table 5.

| Parameter | Rating |
|---|--|
| V_{DD} to V_{SS} | 35 V |
| V_{DD} to GND | -0.3 V to +25 V |
| V_{SS} to GND | +0.3 V to -25 V |
| Analog Inputs ¹ | $V_{SS} - 0.3$ V to $V_{DD} + 0.3$ V or 30 mA, whichever occurs first |
| Digital Inputs ¹ | GND - 0.3 V to $V_{DD} + 0.3$ V or 30 mA, whichever occurs first |
| Peak Current, S or D (Pulsed at 1 ms, 10% Duty-Cycle Maximum) | |
| 8-Lead MSOP (4-Layer Board) | 400 mA |
| 8-Lead LFCSP | 600 mA |
| Continuous Current per Channel, S or D | Data in Table 4 + 15% mA |
| Operating Temperature Range | |
| Industrial | -40°C to +125°C |
| Storage Temperature Range | -65°C to +150°C |
| Junction Temperature | 150°C |
| Reflow Soldering Peak Temperature, Pb Free | 260°C |

¹ Over voltages at IN, S, or D are clamped by internal diodes. Current should be limited to the maximum ratings given.

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

THERMAL RESISTANCE

Table 6. Thermal Resistance

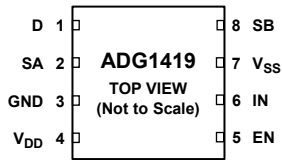
| Package Type | θ_{JA} | θ_{JC} | Unit |
|-----------------------------|---------------|---------------|------|
| 8-Lead MSOP (4-Layer Board) | 206 | 44 | °C/W |
| 8-Lead LFCSP | 50.8 | | °C/W |

ESD CAUTION



ESD (electrostatic discharge) sensitive device. Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

PIN CONFIGURATIONS AND FUNCTION DESCRIPTIONS



NOTES

1. EXPOSED PAD TIED TO SUBSTRATE, V_{SS} .

Figure 3. 8-Lead LFCSP Pin Configuration

08485-003

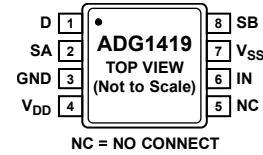


Figure 4. 8-Lead MSOP Pin Configuration

08485-004

Table 7. Pin Function Descriptions

| Pin No. | | Mnemonic | Description |
|----------------|----------------|----------|--|
| LFCSP | MSOP | | |
| 1 | 1 | D | Drain Terminal. This pin can be an input or output. |
| 2 | 2 | SA | Source Terminal. This pin can be an input or output. |
| 3 | 3 | GND | Ground (0 V) Reference. |
| 4 | 4 | V_{DD} | Most Positive Power Supply Potential. |
| 5 | Not applicable | EN | Active High Digital Input. When this pin is low, the device is disabled and all switches are turned off. When this pin is high, the IN logic input determines which switch is turned on. |
| Not applicable | 5 | NC | No Connect. |
| 6 | 6 | IN | Logic Control Input. |
| 7 | 7 | V_{SS} | Most Negative Power Supply Potential. |
| 8 | 8 | SB | Source Terminal. This pin can be an input or output. |
| 0 | Not applicable | EPAD | Exposed Pad. Exposed pad tied to substrate, V_{SS} . |

Table 8. 8-Lead LFCSP Truth Table

| EN | IN | Switch A | Switch B |
|----|----|----------|----------|
| 0 | X | Off | Off |
| 1 | 0 | On | Off |
| 1 | 1 | Off | On |

Table 9. 8-Lead MSOP Truth Table

| IN | Switch A | Switch B |
|----|----------|----------|
| 0 | On | Off |
| 1 | Off | On |

TYPICAL PERFORMANCE CHARACTERISTICS

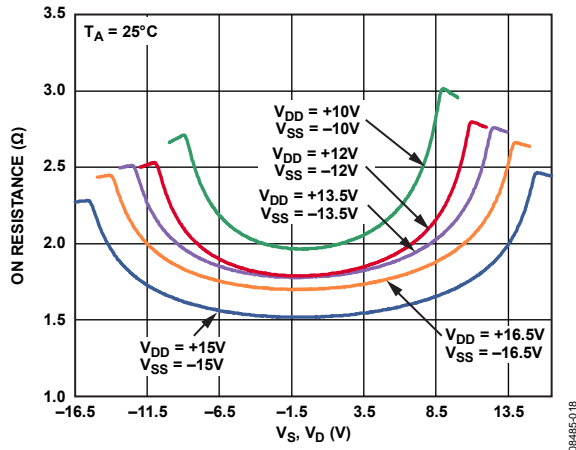


Figure 5. On Resistance as a Function of V_D (V_S) for Dual Supply

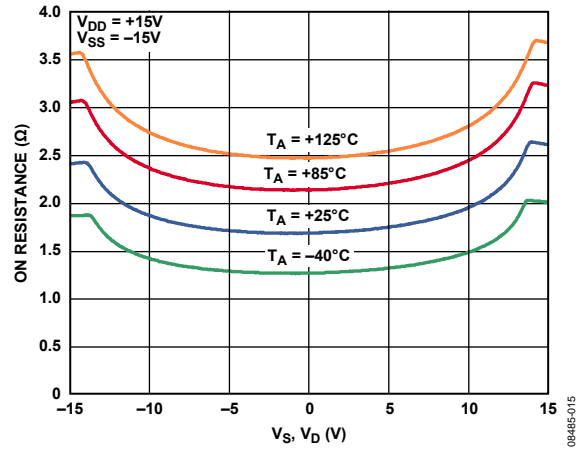


Figure 8. On Resistance as a Function of V_D (V_S) for Different Temperatures, ± 15 V Dual Supply

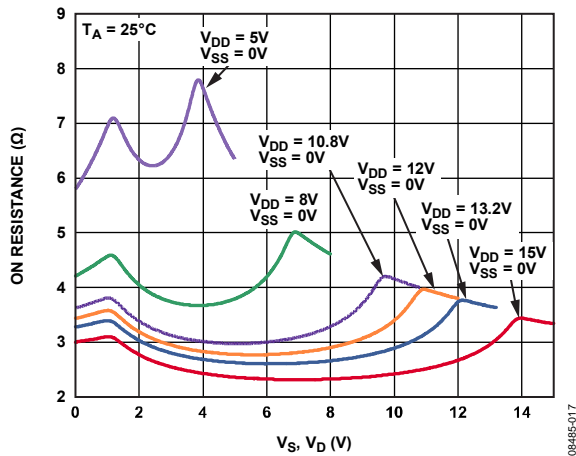


Figure 6. On Resistance as a Function of V_D (V_S) for Single Supply

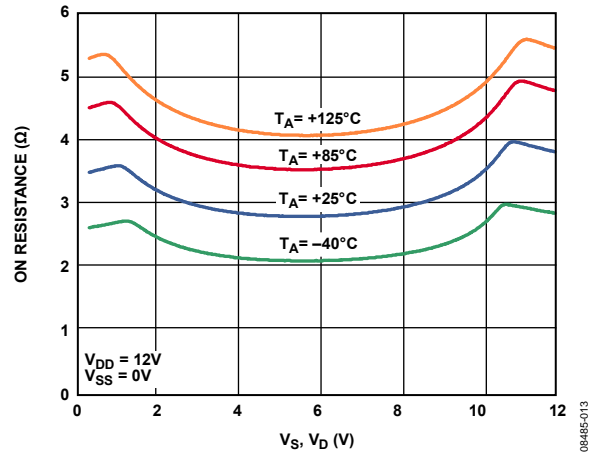


Figure 9. On Resistance as a Function of V_D (V_S) for Different Temperatures, +12 V Single Supply

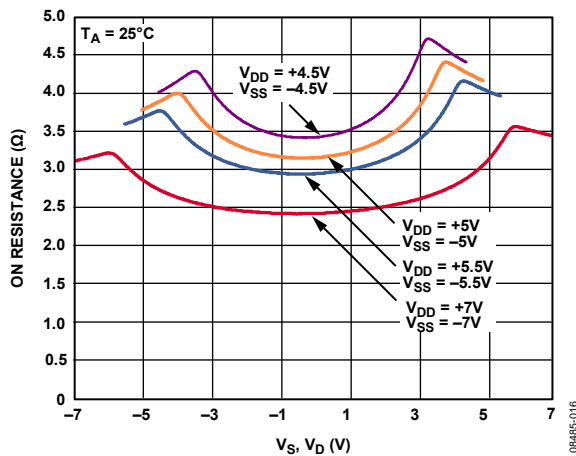


Figure 7. On Resistance as a Function of V_D (V_S) for Dual Supply

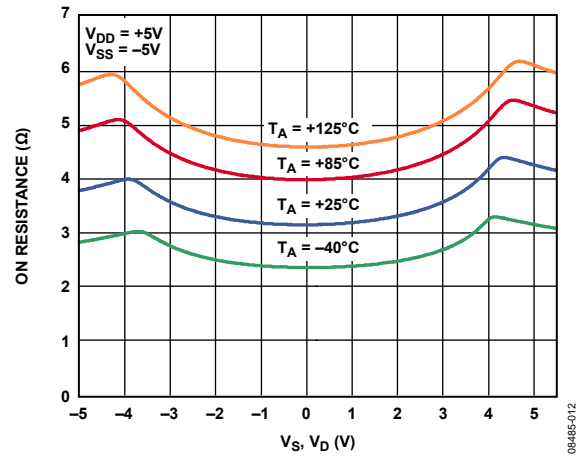


Figure 10. On Resistance as a Function of V_D (V_S) for Different Temperatures, ± 5 V Dual Supply

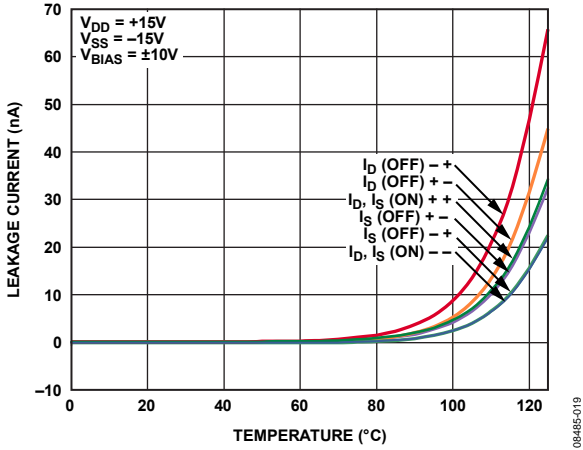


Figure 11. Leakage Currents as a Function of Temperature, ±15 V Dual Supply

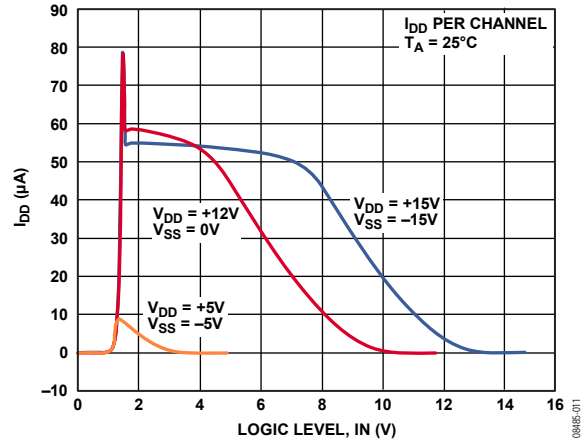


Figure 14. I_{DD} vs. Logic Level

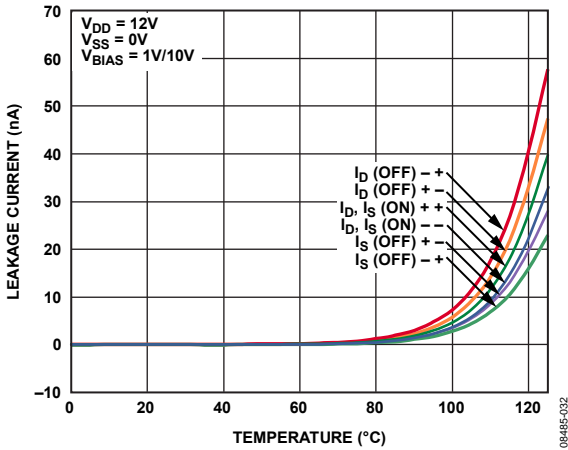


Figure 12. Leakage Currents as a Function of Temperature, +12 V Single Supply

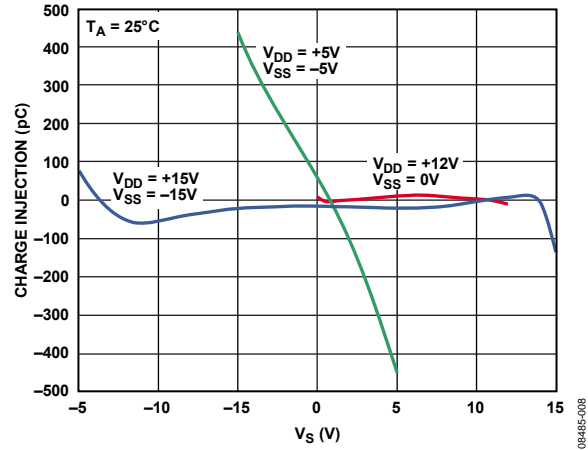


Figure 15. Charge Injection vs. Source Voltage

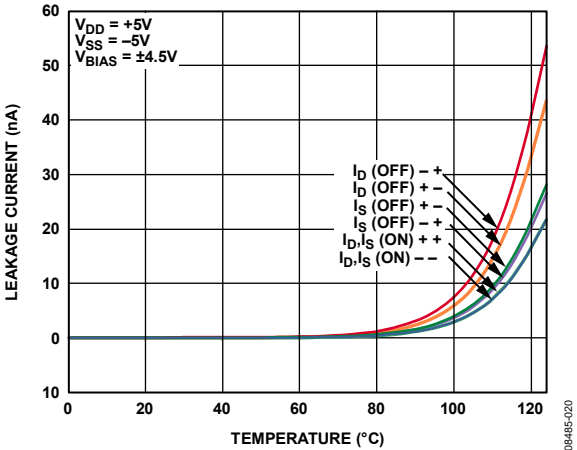


Figure 13. Leakage Currents as a Function of Temperature, ±5 V Dual Supply

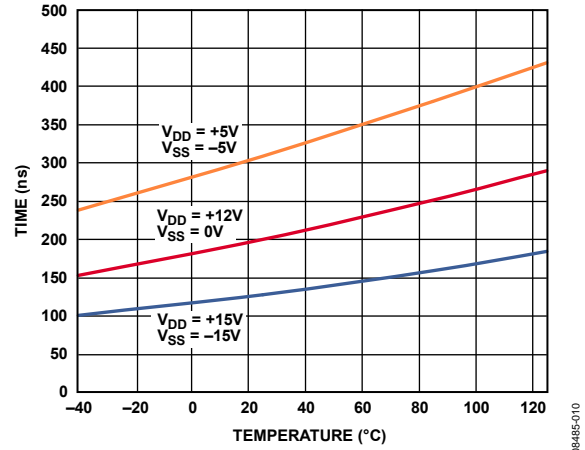


Figure 16. $t_{TRANSITION}$ Times vs. Temperature

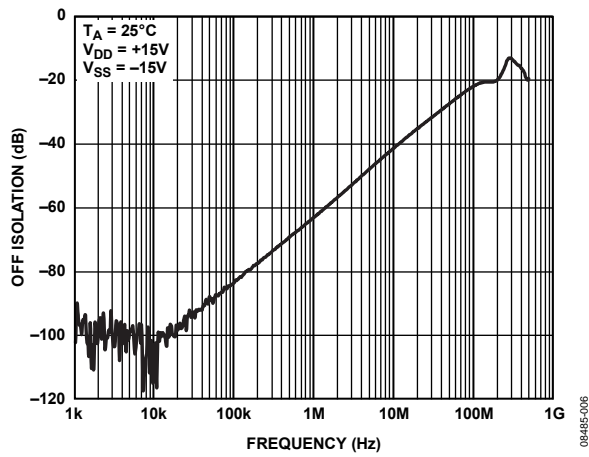


Figure 17. Off Isolation vs. Frequency

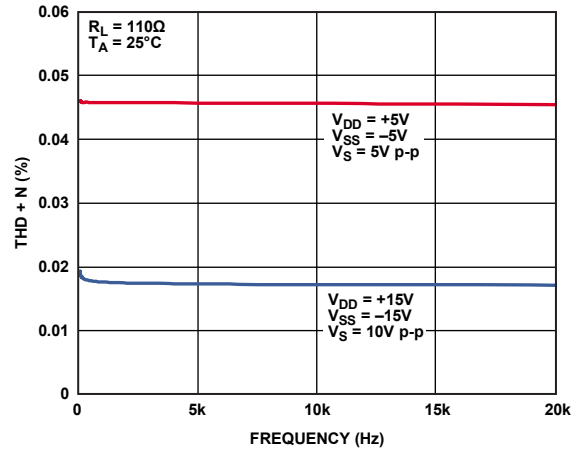


Figure 20. THD + N vs. Frequency

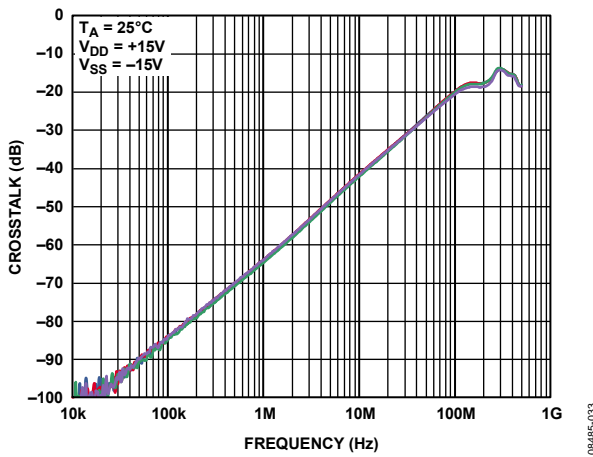


Figure 18. Crosstalk vs. Frequency

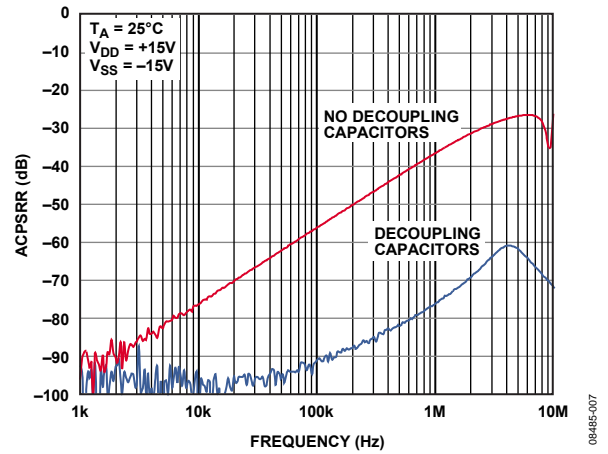


Figure 21. ACPSRR vs. Frequency

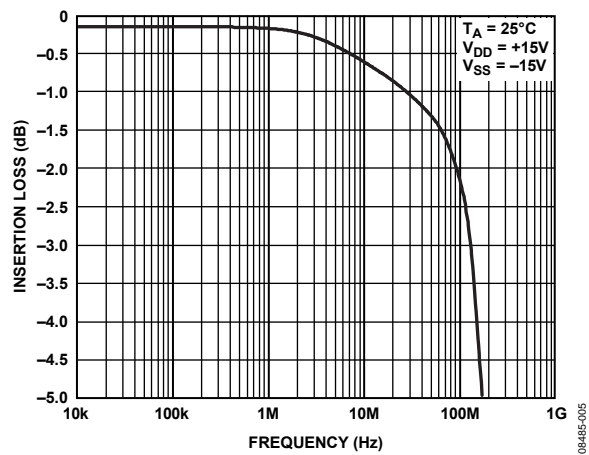


Figure 19. On Response vs. Frequency

TEST CIRCUITS

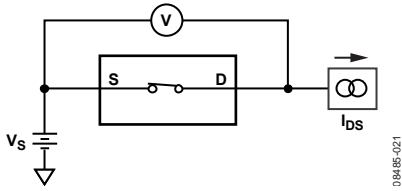


Figure 22. On Resistance

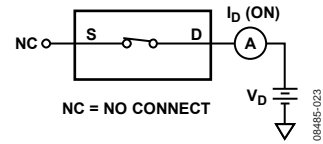


Figure 24. On Leakage

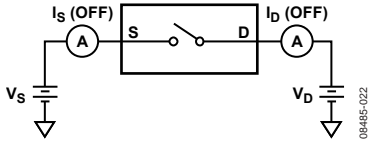


Figure 23. Off Leakage

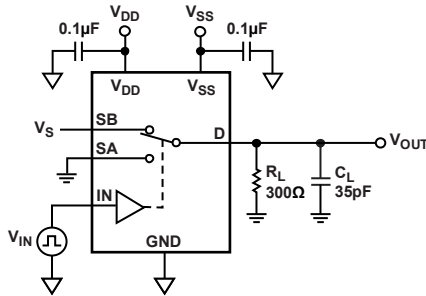


Figure 25. Switching Times, t_{ON} and t_{OFF}

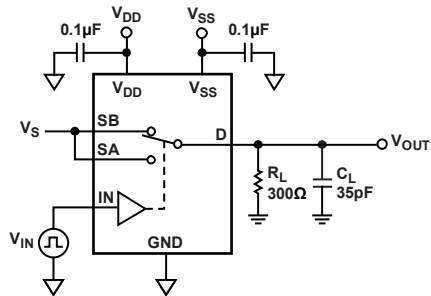
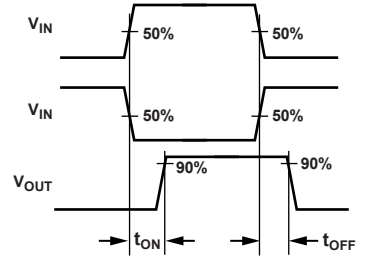


Figure 26. Break-Before-Make Time Delay

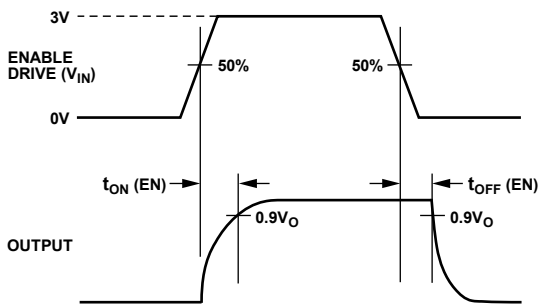
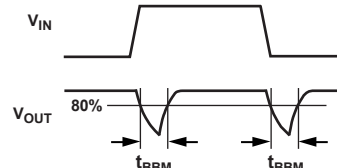
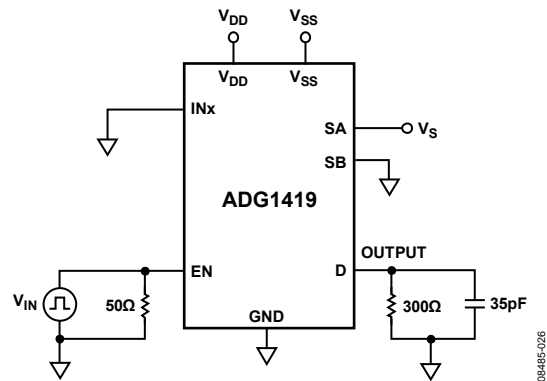


Figure 27. Enable Delay, $t_{ON} (EN)$, $t_{OFF} (EN)$



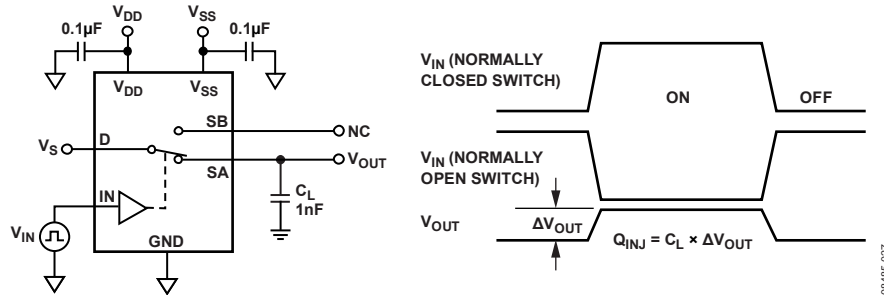


Figure 28. Charge Injection

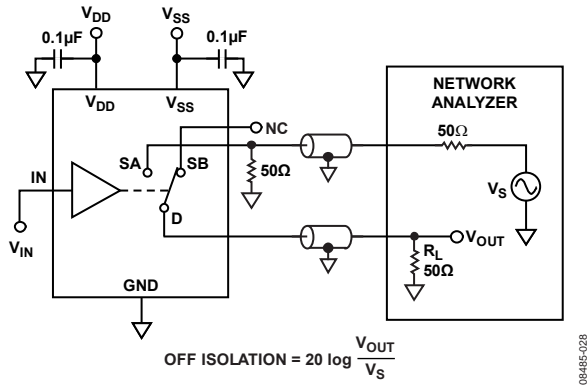


Figure 29. Off Isolation

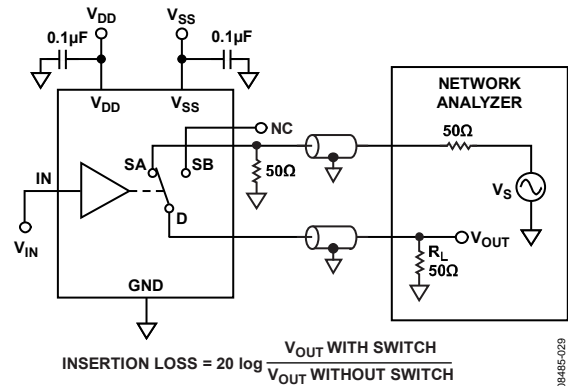


Figure 31. Bandwidth

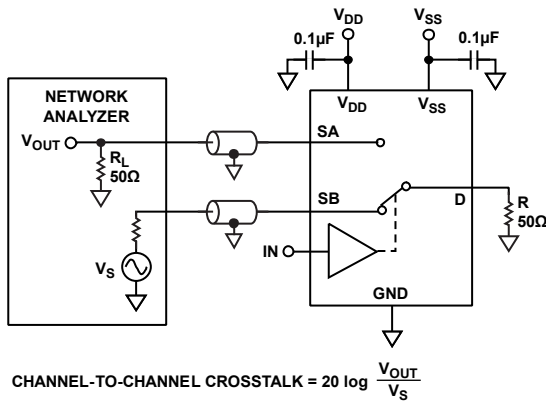


Figure 30. Channel-to-Channel Crosstalk

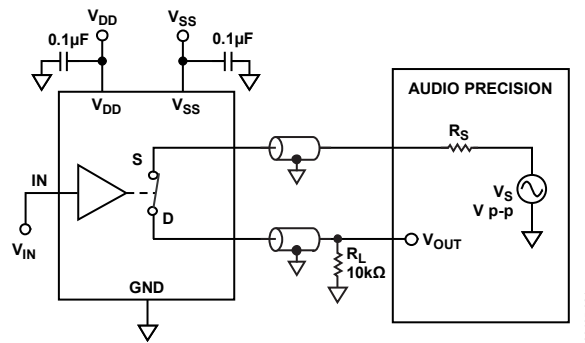
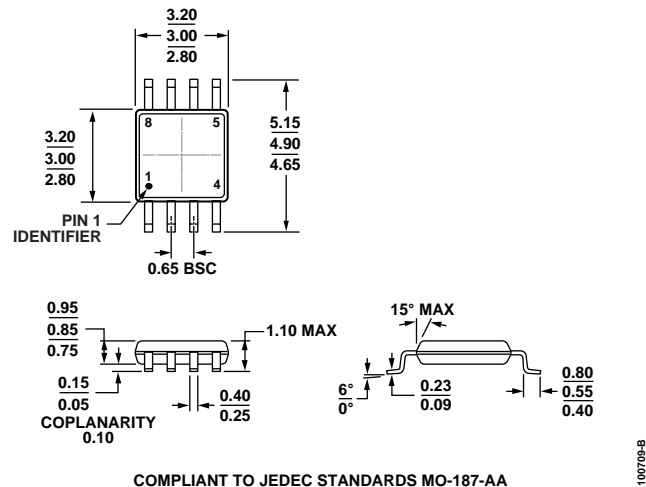


Figure 32. THD + N

TERMINOLOGY

| | | | |
|--|--|---|---|
| I_{DD} | The positive supply current. | t_{ON} (EN) | Delay time between the 50% and 90% points of the digital input and switch on condition. See Figure 27. |
| I_{SS} | The negative supply current. | t_{OFF} (EN) | Delay time between the 50% and 90% points of the digital input and switch off condition. See Figure 27. |
| V_D (V_S) | The analog voltage on Terminal D and Terminal S. | t_{TRANSITION} | Delay time between the 50% and 90% points of the digital inputs and the switch on condition when switching from one address state to another. |
| R_{ON} | The ohmic resistance between Terminal D and Terminal S. | T_{BBM} | Off time measured between the 80% point of both switches when switching from one address state to another. See Figure 26. |
| R_{FLAT} (ON) | Flatness is defined as the difference between the maximum and minimum value of on resistance as measured over the specified analog signal range. | Charge Injection | A measure of the glitch impulse transferred from the digital input to the analog output during switching. See Figure 28. |
| I_S (Off) | The source leakage current with the switch off. | Off Isolation | A measure of unwanted signal coupling through an off switch. See Figure 29. |
| I_D (Off) | The drain leakage current with the switch off. | Crosstalk | A measure of unwanted signal that is coupled through from one channel to another as a result of parasitic capacitance. See Figure 30. |
| I_D, I_S (On) | The channel leakage current with the switch on. | Bandwidth | The frequency at which the output is attenuated by 3 dB. See Figure 31. |
| V_{INL} | The maximum input voltage for Logic 0. | On Response | The frequency response of the on switch. |
| V_{INH} | The minimum input voltage for Logic 1. | Insertion Loss | The loss due to the on resistance of the switch. See Figure 31. |
| I_{INL} (I_{INH}) | The input current of the digital input. | THD + N | The ratio of the harmonic amplitude plus noise of the signal to the fundamental. See Figure 32. |
| C_S (Off) | The off switch source capacitance, measured with reference to ground. | AC Power Supply Rejection Ratio (ACPSRR) | ACPSRR measures the ability of a part to avoid coupling noise and spurious signals that appear on the supply voltage pin to the output of the switch. The dc voltage on the device is modulated by a sine wave of 0.62 V p-p. The ratio of the amplitude of signal on the output to the amplitude of the modulation is the ACPSRR. See Figure 21. |
| C_D (Off) | The off switch drain capacitance, measured with reference to ground. | | |
| C_D, C_S (On) | The on switch capacitance, measured with reference to ground. | | |
| C_{IN} | The digital input capacitance. | | |

OUTLINE DIMENSIONS



COMPLIANT TO JEDEC STANDARDS MO-187-AA
 Figure 33. 8-Lead Mini Small Outline Package [MSOP]
 (RM-8)
 Dimensions shown in millimeters

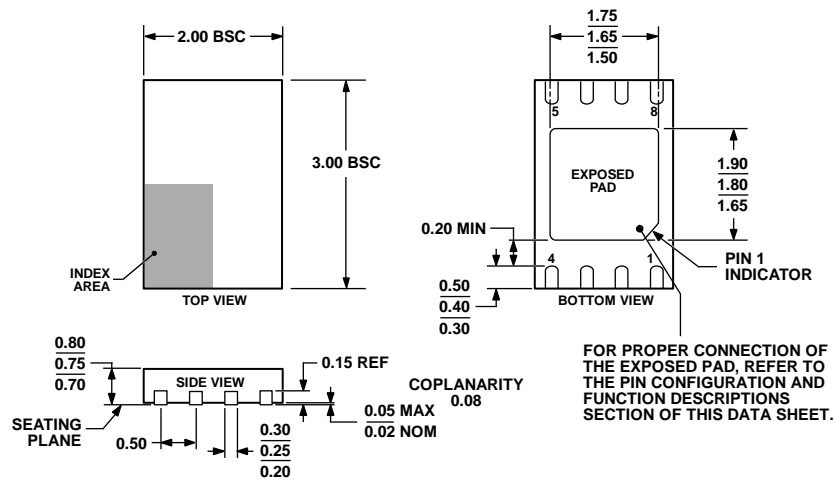


Figure 34. 8-Lead Lead Frame Chip Scale Package [LFCSP_WD]
 3 mm x 2 mm Body, Very Very Thin, Dual Lead
 (CP-8-4)
 Dimensions shown in millimeters

ORDERING GUIDE

| Model ¹ | Temperature Range | Package Description | Package Option | Branding |
|--------------------|-------------------|---|----------------|----------|
| ADG1419BRMZ | -40°C to +125°C | 8-Lead Mini Small Outline Package [MSOP] | RM-8 | S1L |
| ADG1419BRMZ-REEL7 | -40°C to +125°C | 8-Lead Mini Small Outline Package [MSOP] | RM-8 | S1L |
| ADG1419BCPZ-REEL7 | -40°C to +125°C | 8-Lead Lead Frame Chip Scale Package [LFCSP_WD] | CP-8-4 | 1C |

¹ Z = RoHS Compliant Part.

NOTES